Ai-M61-32SU Specification

Version V1.0.1

Document resume

Version	Date	Develop/revise content	Edition	Approve
V1.0.0	2023.03.23	First Edition	Shengxin Zou	Ning Guan
V1.0.1	2023.11.17	1、Update the chip block diagram and the supported peripheral interfaces; 2、Add important statements	Ning Guan	Hong Xu

Content

1. Product Overview

Ai-M61-32SU is a Wi-Fi 6+BLE5.3 module developed by Shenzhen Ai-Thinker Technology Co., Ltd. The module is equipped with a BL618 chip as the core processor and supports Wi-Fi 802.11b/g/n/ax Protocol and BLE protocol, support Thread protocol. The BL618 system includes a low-power 32-bit RISC-V CPU with a floating point unit, DSP unit, cache and memory, and the highest frequency can reach 320M.

The Ai-M61-32SU module has rich peripheral interfaces, including Camera, MJPEG, Dispaly, Audio Codec, USB2.0, SDU, Ethernet (EMAC), SD/MMC (SDH), SPI, UART, I2C, I2S, PWM, GPDAC, GPADC, ACOMP, GPIO, etc. It can be widely used in audio and video multimedia, Internet of Things (IoT), mobile devices, wearable electronic devices, smart home and other fields.

Ai-M61-32SU module Sec Eng module supports AES/SHA/PKA/TRNG and other functions, supports image encryption and signature startup, and meets various security application requirements in the Internet of Things field.

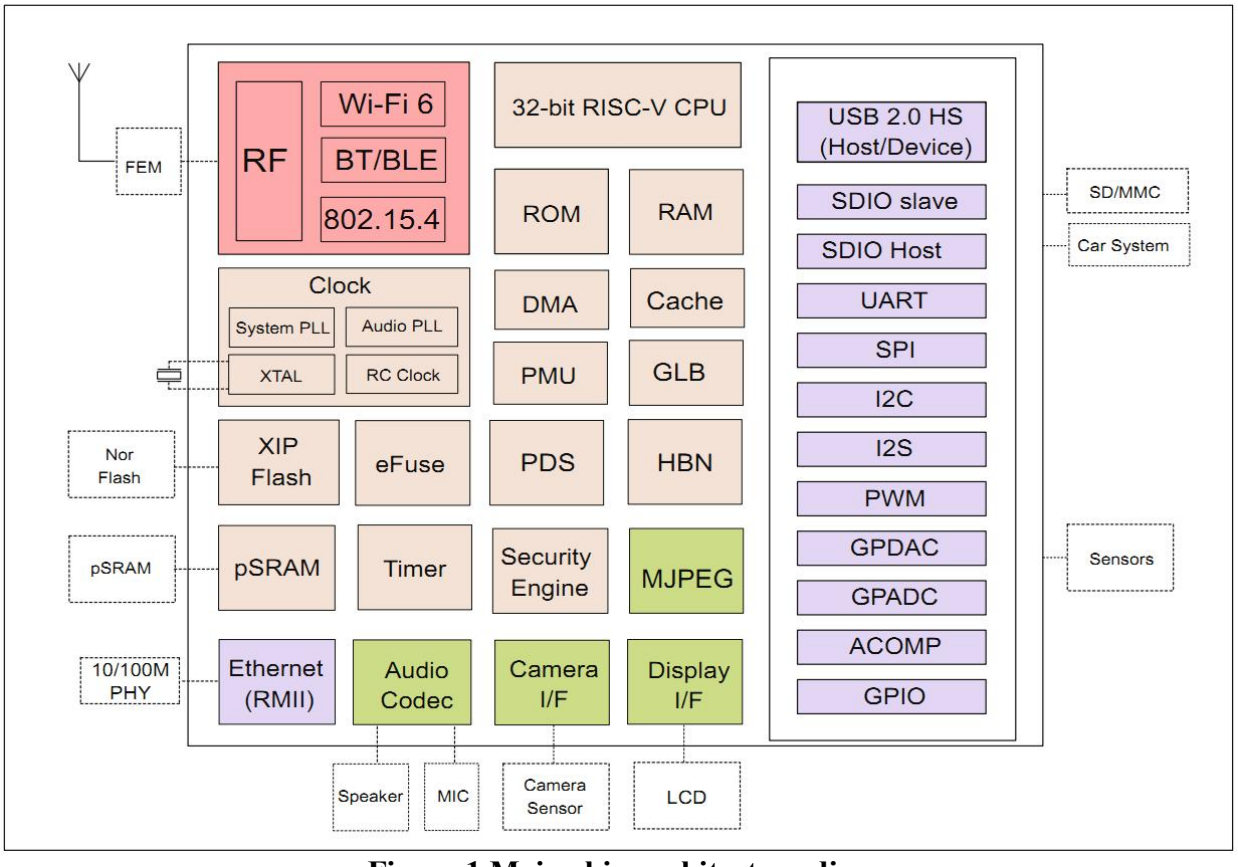


Figure 1 Main chip architecture diagram

1.1. Characteristic

- The package is SMD-41

- Support 2.4GHz working frequency band
- Support IEEE 802.11 b/g/n/ax
- Support BLE5.3
- Support Thread
- Support Wi-Fi/BLE/Thread coexistence
- Wi-Fi security supports WPS/WEP/WPA/WPA2/WPA3
- Support 20/40MHz bandwidth, 1T1R, maximum rate 229.4 Mbps
- Support STA, SoftAP, STA+SoftAP and sniffer mode
- 32-bit RISC-V CPU with FPU and DSP, the highest frequency can reach 320M
- 4MB pSRAM，532KB SRAM，128KB ROM，4Kb eFuse
- Support Camera,MJPEG, Dispaly, Audio Codec, USB2.0, SDU, Ethernet (EMAC), SD/MMC (SDH), SPI, UART, I2C, I2S, PWM, GPDAC, GPADC, ACOMP and GPIO, etc.
- Support Camera Sensor DVP interface
- Support Video Codec MJPEG encoding
- Support LCD display (QSPI, DBI and RGB)
- Integrated RF Balun、PA/LNA
- Support secure boot; secure debugging
- Support XIP QSPI On-The-Fly AES Decryption (OTFAD)
- Support TrustZone
- Support AES-CBC/CCM/GCM/XTS mode
- Support MD5、SHA-1/224/256/384/512
- Support TRNG（True Random Number Generator）
- Support PKA (Public Key Accelerator) for RSA/ECC
- Wi-Fi fast connection with BLE support
- Universal AT instruction for quick start
- Support secondary development, integrated Windows, Linux development environment

2. Main parameters

Table 1 Description of the main parameters

Model	Ai-M61-32SU
Package	SMD-41
Size	19.2*18.0*3.1(±0.2)mm
Antenna	IPEX connector
Frequency	2400 ~ 2483.5MHz
Operating temperature	-40℃ ~ 85℃
Storage temperature	-40℃ ~ 125℃, < 90%RH
Power supply	Support voltage 2.97V ~ 3.6V， supply current ≥500mA
Interface	Support Camera、MJPEG、Dispaly、Audio Codec、USB2.0、SDU、Ethernet (EMAC)、SD/MMC(SDH)、SPI、UART、I2C、I2S、PWM、GPDAC、GPADC、ACOMP 和 GPIO 等
IO	29
UART rate	Default 115200 bps
Security	WPS/WEP/WPA/WPA2/WPA3
Flash	Default 8MByte,maximum support 16MByte

2.1. Static electricity requirement

Ai-M61-32SU is an electrostatic sensitive device. Therefore, you need to take special precautions when carrying it.

Figure 2 ESD preventive measures

2.2. Electrical characteristics

Table 2 Electrical characteristics table

Parameters		Condition	Min.	Typical value	Max.	Unit
Voltage Supply		VDD	2.97	3.3	3.6	V
I/O	VIL	-	-	-	0.3*VDDIO	V
	VIH	-	0.7*VDDIO	-	-	V
	VOL	-	-	0.1*VDDIO	-	V
	VOH	-	-	0.9*VDDIO	-	V
	IMAX	-	-	-	15	mA

2.3. Wi-Fi RF Performance

Table 3 Wi-Fi RF performance table

Description	Typical value			Unit
Frequency range	2400 ~ 2483.5MHz			MHz
Output Power				
Mode	**Min.**	**Typical**	**Max.**	**Unit**
11ax Mode HE40，PA output power	-	16	-	dBm
11ax Mode HE20，PA output power	-	17	-	dBm
11n Mode HT40， PA output power	-	19	-	dBm
11n Mode HT20， PA output power	-	19	-	dBm
11g Mode, PA output power	-	19	-	dBm
11b Mode, PA output power	-	22	-	dBm
Receive Sensitivity				
Mode	**Min.**	**Typical**	**Max.**	**Unit**
11b， 1 Mbps	-	-98	-	dBm
11b， 11 Mbps	-	-90	-	dBm
11g， 6 Mbps	-	-93	-	dBm
11g， 54 Mbps	-	-76	-	dBm
11n， HT20 (MCS7)	-	-73	-	dBm
11ax， HE20 (MCS9)	-	-70	-	dBm
11ax， HE40 (MCS9)	-	-67	-	dBm

2.4. BLERF Performance

Table 4 BLE RF performance table

Description	Typical value			Unit
Frequency range	2400 ~ 2483.5MHz			MHz
Output Power				
Rate Mode	**Min.**	**Typical**	**Max.**	**Unit**
1Mbps	-	10	15	dBm
2Mbps	-	10	15	dBm
Receive Sensitivity				
Rate Mode	**Min.**	**Typical**	**Max.**	**Unit**
1Mbps sensitivity@30.8%PER	-	-99	-	dBm
2Mbps sensitivity@30.8%PER	-	-97	-	dBm

2.5. Power

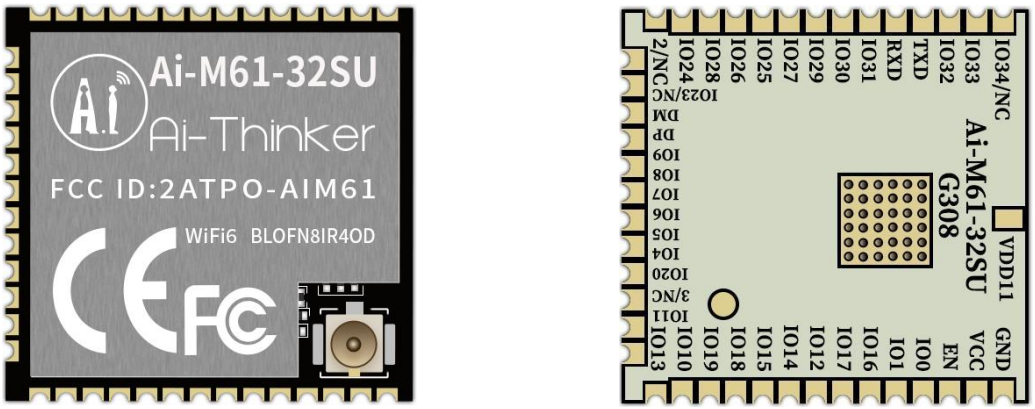
The following power consumption data is based on a 3.3V power supply and an ambient temperature of 25°C.

- POUT power for all transmit modes is measured at the antenna interface.
- All emission data is based on 100% duty cycle, measured in continuous emission mode.

Table 5 Power consumption

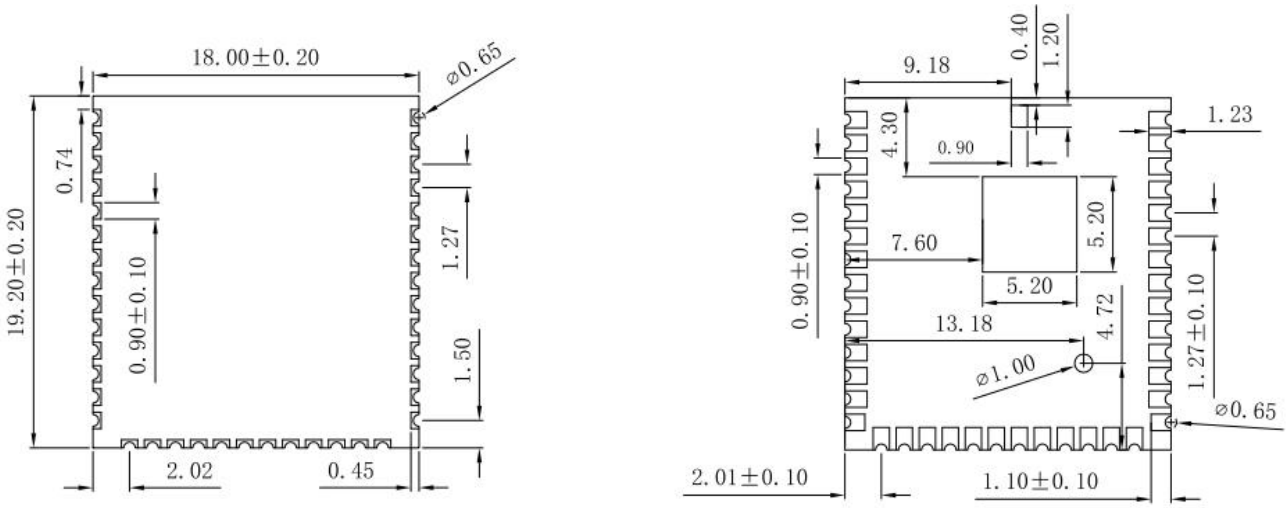
Mode	Min.	AVG	Max.	Unit
Tx 802.11b，11Mbps，POUT=+22dBm	-	374	-	mA
Tx 802.11g， 54Mbps， POUT =+19dBm	-	331	-	mA
Tx 802.11n， MCS7， POUT =+19dBm	-	328	-	mA
Tx 802.11ax， MCS7， POUT =+19dBm	-	293	-	mA
Rx 802.11b，packet length 1024 byte	-	64	-	mA
Rx 802.11g，packet length 1024 byte	-	64	-	mA
Rx 802.11n，packet length 1024 byte	-	64	-	mA
Rx 802.11ax，packet length 1024 byte	-	64	-	mA

3. Appearance Dimensions



Front Back

Figure 3 Appearance (the rendering is for reference only, the actual object shall prevail)



Front Back

Figure 4 Dimension diagram

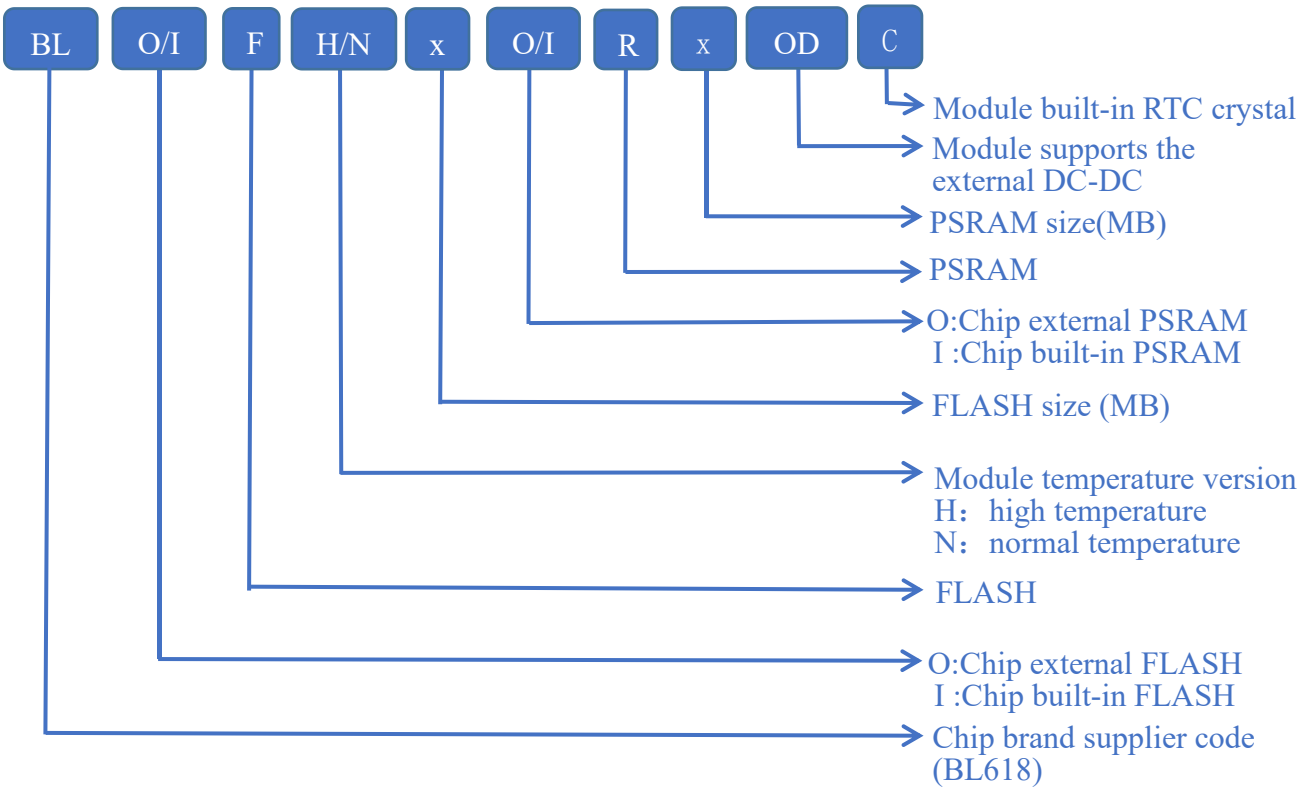


Figure 5 Shield printing information

4. Pin Definition

The Ai-M61-32SU module has a total of 41 pins connected, such as the pin schematic diagram, and the pin function definition table is the interface definition.

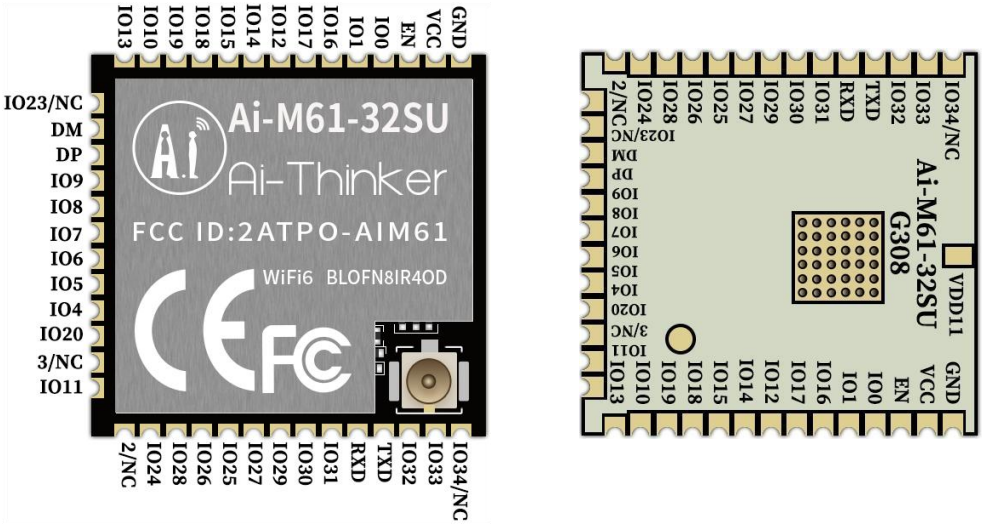


Figure 6 Schematic diagram of module pins

Table 6 Pin function definition table

No	Name	Function
1	GND	Ground
2	VCC	3.3V power supply; the output current of the external power supply is recommended to be above 500mA
3	EN	Default as chip enable, active high
4	IO0	GPIO0/SPI_SS/I2S_BCLK/I2C_SCL/PWM0/ADC_CH9
5	IO1	GPIO1/SPI_SCLK/I2S_FS/I2C_SDA/PWM0/ADC_CH8
6	IO16/NC	Available by default, this IO port is shared with the 32.768KHz crystal oscillator input pin inside the module. If you customize a module with an internal patch 32.768KHz crystal oscillator, the IO will be in NC state. GPIO16/SPI_SS/I2S_BCLK/I2C_SCL/XTAL_32K_IN/PWM0
7	IO17/NC	Available by default, this IO port is shared with the internal 32.768KHz crystal oscillator output PIN of the module. If you customize a module with an internal patch 32.768KHz crystal oscillator, the IO will be in NC state. GPIO17/SPI_SCLK/I2S_FS/I2C_SDA/XTAL_32K_OUT/PWM0
8	IO12	GPIO12/SPI_SS/SDH_CLK/SF3_D0/I2S_BCLK/I2C_SCL/PWM0/ADC_CH6
9	IO14	GPIO14/SPI_MOSI/SPI_MISO/SDH_DAT3/SF3_D1/I2S_DI/I2S_RCLK_O/I2C_SCL/PWM0/ADC_CH4
10	IO15	GPIO15/SPI_MOSI/SDH_DAT2/SF3_CS/I2S_DO/I2S_RCLK_O/I2C_SDA/PWM0
11	IO18	GPIO18/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/PWM0
12	IO19	GPIO19/SPI_MOSI/I2S_DO/I2S_RCLK_O/I2C_SDA/PWM0/ADC_CH1
13	IO10	GPIO10/SPI_MISO/SDH_DAT1/SF2_D3/I2S_DI/I2S_RCLK_O/I2C_SCLPWM0/ADC_CH7
14	IO13	GPIO13/SPI_SCLK/SDH_CMD/SF3_D2/I2S_FS/I2C_SDA/PWM0/ADC_CH5
15	IO11	GPIO11/SPI_MOSI/SDH_DAT0/SF3_CLK/I2S_DO/I2S_RCLK_O/I2C_SDA/PWM0
16	IO3/NC	The default is NC, which cannot be used. If you need to use it, please contact Ai-Thinker. GPIO3/SPI_MOSI/I2S_DO/I2S_RCLK_O/I2C_SDA/PWM0/ADC_CH3
17	IO20	GPIO20/SPI_SS/I2S_BCLK/I2C_SCL/PWM0/ADC_CH0

18-23	IO4-IO9	The default is NC, which cannot be used. This IO port is shared with the module's Flash pin, and cannot be used in the state of external FLASH
24	USB-DP	USB_DP
25	USB-DM	USB_DM
26	IO23	GPIO23/SPI_MOSI/I2S_DO/I2S_RCLK_O/I2C_SDA/PWM0
27	IO2/NC	The default is NC, which cannot be used. If you need to use it, please contact Ai-Thinker. GPIO2/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/PWM0/ADC_CH2
28	IO24	GPIO24/SPI_SS/I2S_BCLK/I2C_SCL/PWM0
29	IO28	GPIO28/SPI_SS/I2S_BCLK/I2C_SCL/PWM0/ADC_CH11
30	IO26	GPIO26/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/PWM0
31	IO25	GPIO25/SPI_SCLK/I2S_FS/I2C_SDA/PWM0
32	IO27	GPIO27/SPI_MOSI/I2S_DO/I2S_RCLK_O/I2C_SDA/PWM0/ADC_CH10
33	IO29	GPIO29/SPI_SCLK/I2S_FS/I2C_SDA/PWM0
34	IO30	GPIO30/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/PWM0
35	IO31	GPIO31/SPI_MOSI/I2S_DO/I2S_RCLK_O/I2C_SDA/PWM0
36	RXD	RXD/GPIO22/SPI_MOSI/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/PWM0
37	TXD	TXD/GPIO21/SPI_SCLK/I2S_FS/I2C_SDA/PWM0
38	IO32	GPIO32/SPI_SS/I2S_BCLK/I2C_SCL/PWM0
39	IO33	GPIO33/SPI_SCLK/I2S_FS/I2C_SDA/PWM0
40	IO34/NC	The default is NC, which cannot be used. If you need to use it, please contact Ai-Thinker. GPIO2/SPI_MISO/I2S_DI/I2S_RCLK_O/I2C_SCL/PWM0
41	VDD11	Use external power supply 1.1V input for ultra-low power consumption
Note: 1. GPIO2 is used as Bootstrap. When the power level is high at the moment of power-on, the module enters the programming mode; when the power is low at the moment of power-on, the module starts normally.		

5. Schematic

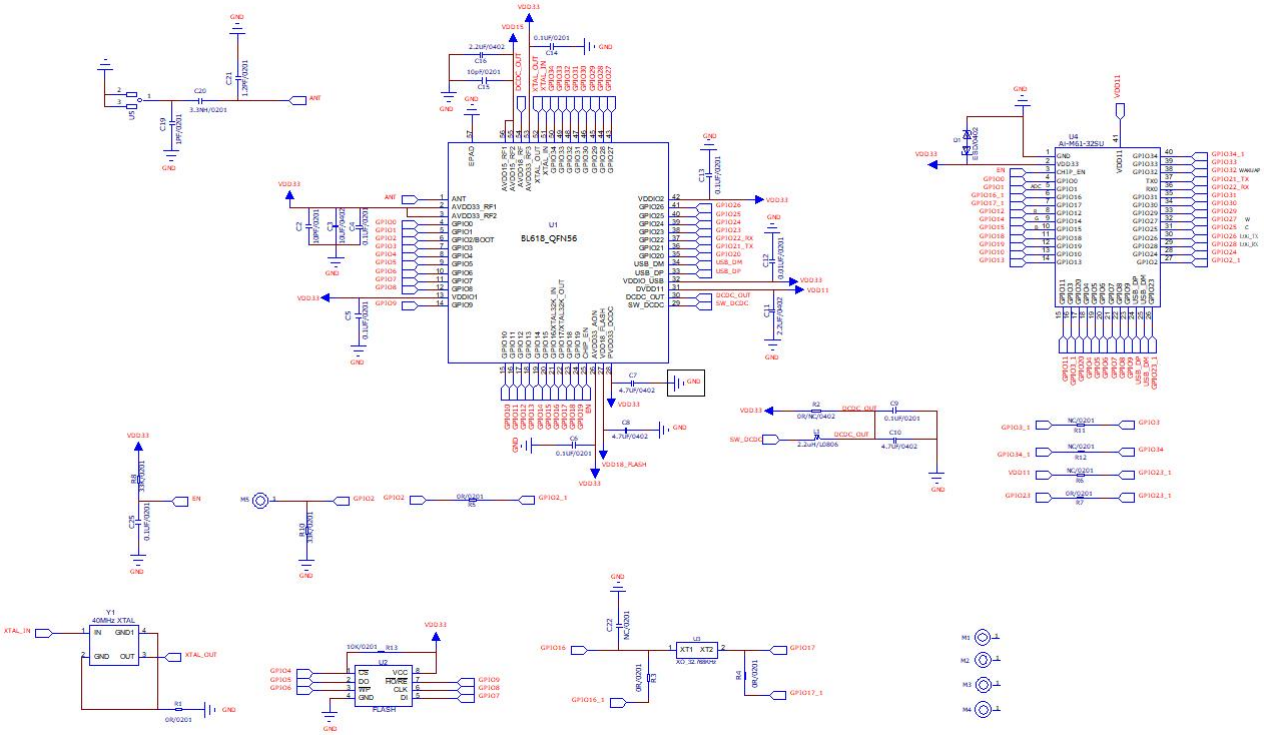


Figure 7 Module schematic

6. Design Guidance

6.1. Module application circuit

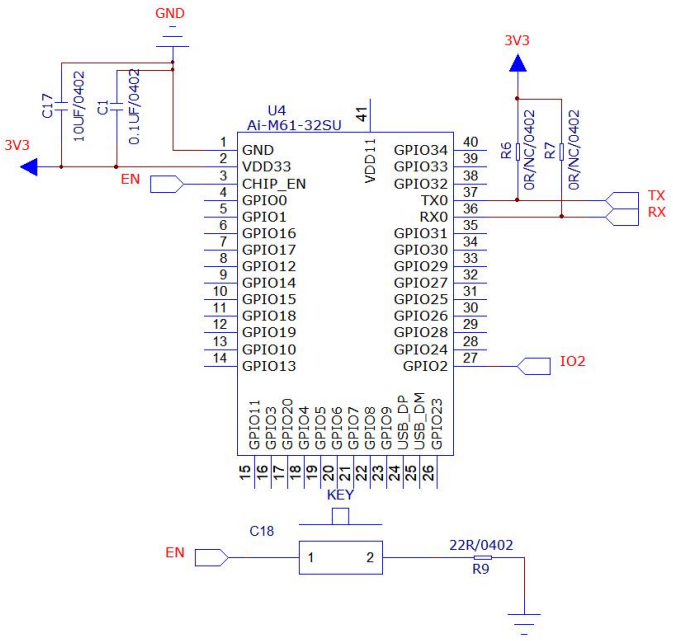


Figure 8 Application circuit diagram

- GPIO2 is the module startup control pin. It is in the normal working mode when it is low level, and it is in the firmware burning mode when it is high level. The default low level inside the chip.
- GPIO2/NC, not available by default.
- GPIO16/GPIO17，available by default. These IO ports are shared with the internal 32.768KHz crystal oscillator pins of the module. If you customize a module with an internal patch 32.768KHz crystal oscillator, the IO will be in NC state.
- GPIO4/GPIO5/GPIO6/GPIO7/GPIO8/GPIO9 are NC by default and cannot be used. This IO port is shared with the module's Flash pin, and cannot be used when the external FLASH is connected.
- GPIO3/GPIO34is NC by default and cannot be used. If you need to use it, please contact Ai-Thinker.

6.2. Recommended PCB package size

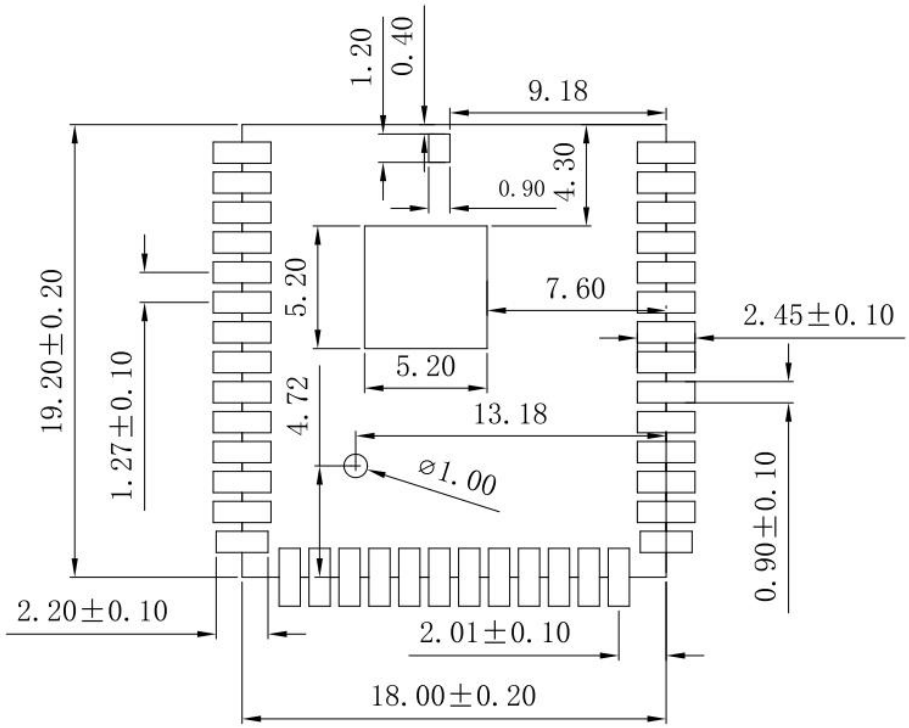


Figure 9 Recommended PCB Package Dimensions

6.3. Antenna layout requirements

- For the installation position on the motherboard, the following two methods are recommended:

Solution 1: Put the module on the edge of the motherboard, and the antenna area extends out of the edge of the motherboard.

Solution 2: Put the module on the edge of the motherboard, and hollow out an area on the edge of the motherboard where the antenna is.

- In order to meet the performance of the on-board antenna, it is forbidden to place metal parts around the antenna and keep away from high-frequency devices.

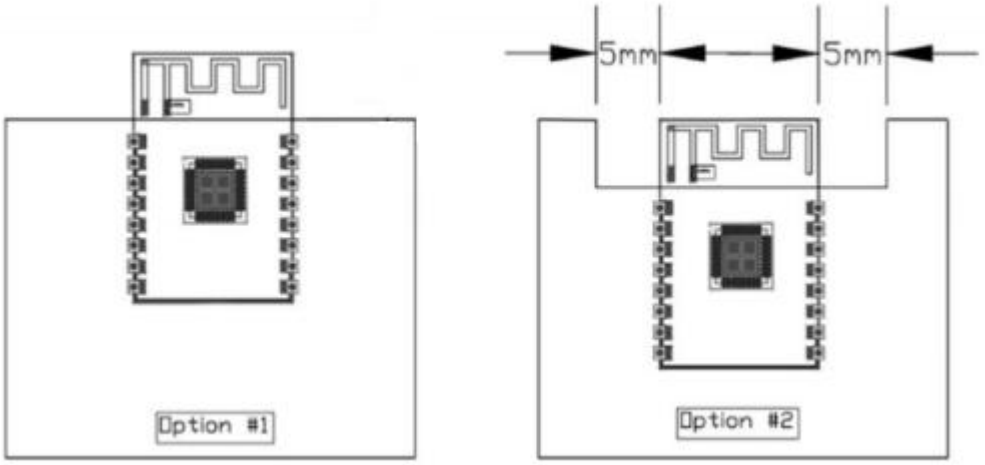


Figure 10 Antenna layout diagram

6.4. Power supply

- Recommended 3.3V voltage, peak current above 500mA.
- It is recommended to use LDO power supply; if using DC-DC, it is recommended to control the ripple within 30mV.
- It is recommended to reserve the position of the dynamic response capacitor for the DC-DC power supply circuit, which can optimize the output ripple when the load changes greatly.
- It is recommended to add an ESD device to the 3.3V power interface.

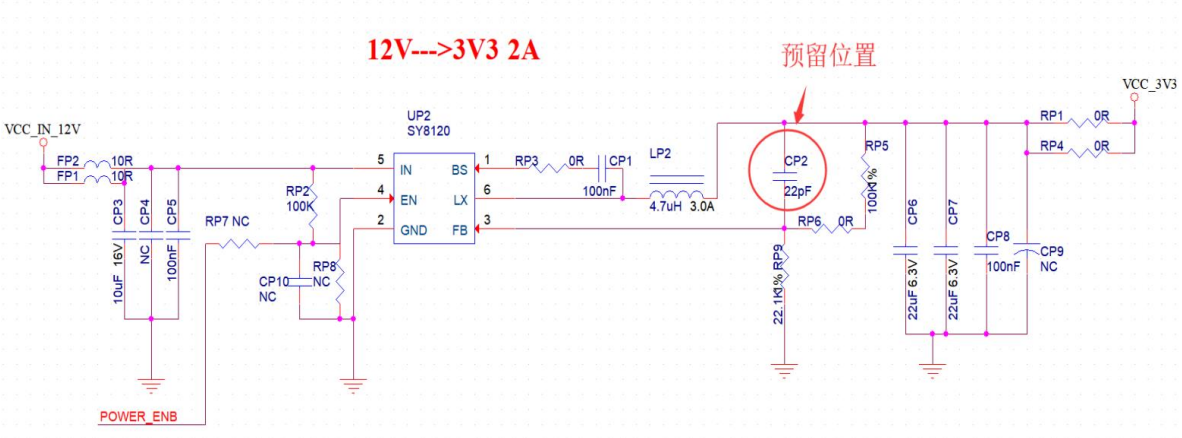


Figure 11 DC-DC step-down circuit diagram

6.5. GPIO

- There are some IO ports on the periphery of the module. If you need to use it, it is recommended to connect a 10-100 ohm resistor in series with the IO ports. This can suppress overshoot and make the levels on both sides more stable. Helpful for both EMI and ESD.
- For the pull-up and pull-down of the special IO port, please refer to the instructions in the specification, which will affect the startup configuration of the module.
- The IO port of the module is 3.3V. If the level of the main control and the IO port of the module do not match, a level conversion circuit needs to be added.
- If the IO port is directly connected to the peripheral interface, or terminals such as pin headers, it is recommended to reserve an ESD device near the IO port wiring near the terminal.

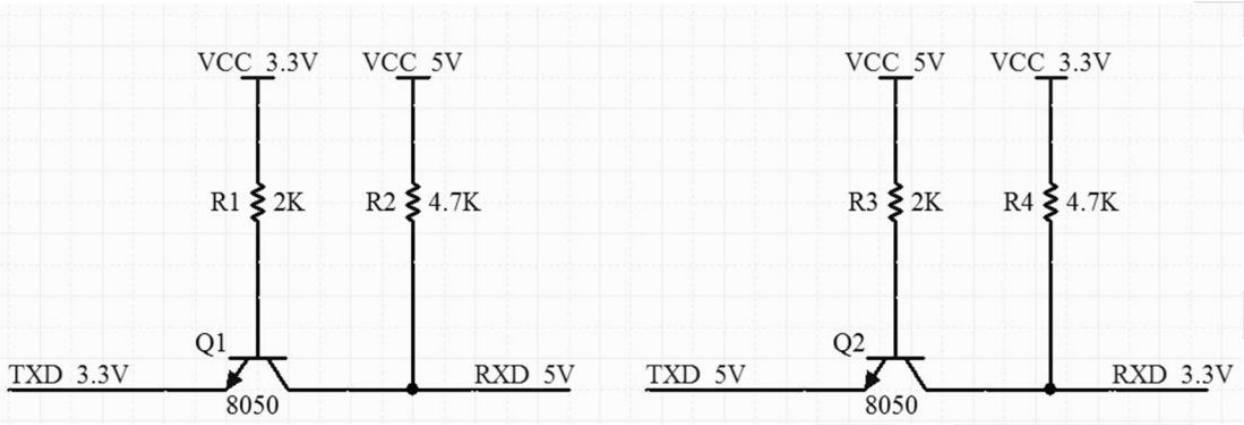


Figure 12 Level convert circuit

7. Storage conditions

Products sealed in moisture-proof bags should be stored in a non-condensing atmosphere at <40°C/90%RH.

The moisture sensitivity level MSL of the module is 3.

After the vacuum bag is unpacked, it must be used within 168 hours at 25±5°C/60%RH, otherwise it needs to be baked before it can be put online again.

8. Reflow welding curve diagram

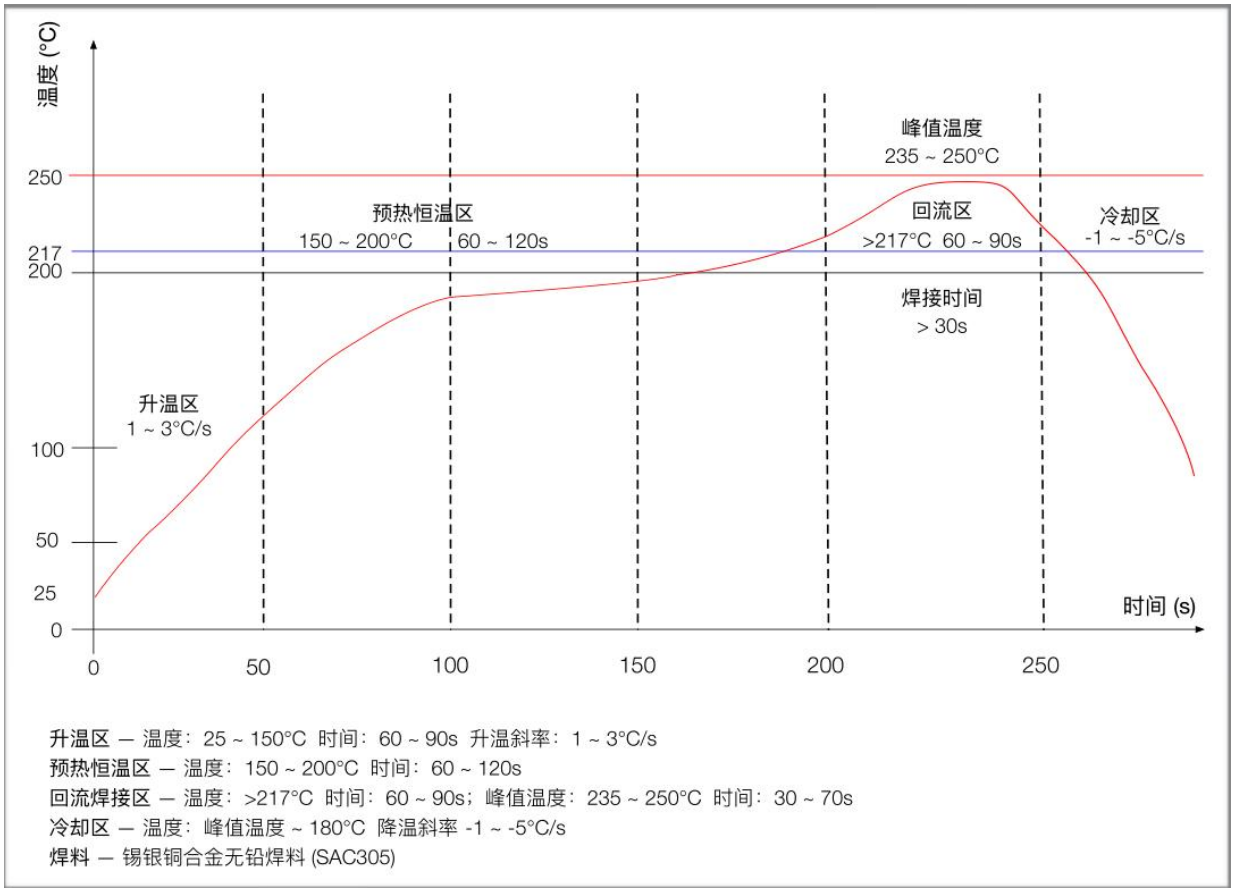


Figure 13 Reflow welding diagram

9. Product Packaging Information

Ai-M61-32SUmodule is packaged in a tape, 700pcs/reel.As shown in the below image:

Figure 14 Package and packing diagram

10.Contact us

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